


METHODS FOR PLANARIZATION OF METAL-CONTAINING SURFACES  
USING HALOGENS AND HALIDE SALTS

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Abstract of the Disclosure

A planarization method includes providing a metal-containing surface (preferably, a Group VIII metal-containing surface, and more preferably a platinum-containing surface) and positioning it for contact with a polishing surface in the presence of a planarization composition that includes a halogen and a halide salt.

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"Express Mail" mailing label number: EV 201890272 US  
Date of Deposit: February 3, 2004  
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